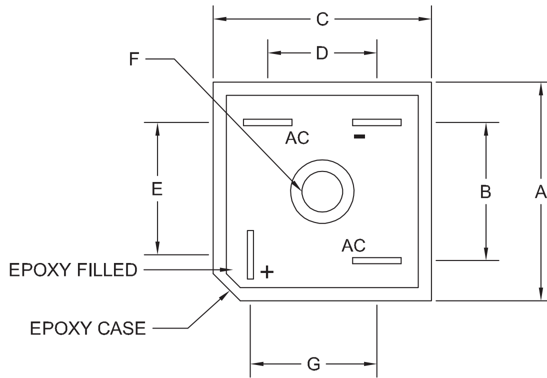
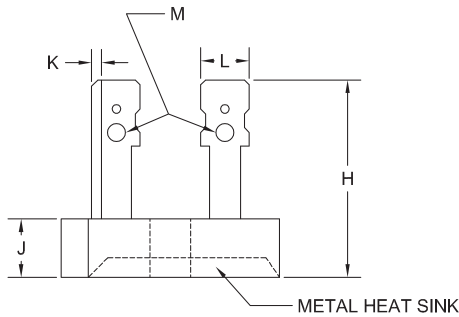
Package Details
Case FP

Mechanical Drawing



DIMENSIONS				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.115	1.135	28.32	28.83
B	0.688	0.732	17.50	18.59
C	1.115	1.135	28.32	28.83
D	0.542	0.582	13.77	14.78
E	0.618	0.672	15.70	17.07
F (DIA.)	0.200	0.220	5.08	5.59
G	0.632	0.672	16.05	17.07
H	0.740	0.849	18.80	21.58
J	0.290	0.334	7.37	8.50
K	0.027	0.035	0.71	0.91
L	0.250		6.35	
M (DIA.)	0.940		2.39	

CASE FP (REV:R2)



Lead Code: As indicated on mechanical drawing.

R2

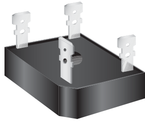
Packing Options

Bulk:
White corrugated box with black conductive lining and bridge inserts.
Bulk Packing Quantity: 100

R1 (20-June 2013)

Material Composition Specification

Case FP



Device average mass . . . . 18.0 g

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.242%	43.58	Si	7440-21-3	0.23%	41.4	2,299
				Ni	7440-02-0	0.012%	2.18	121
leadframe	copper	24.26%	4,367	Cu	7440-50-8	24.26%	4,367	242,611
plating	nickel	0.03%	5.4	Ni	7440-02-0	0.03%	5.4	300
die attach	high temperature solder	13.245%	2,384	Pb	7439-92-1	0.005%	0.945	53
				Sn	7440-31-5	0.0001%	0.05	3
				Cu	7440-50-8	13.24%	2,383	132,392
encapsulation	EMC with aluminum heatsink	62.23%	11,200	epoxy resin	Proprietary	53.57%	9,640	535,556
				Al	7429-90-5	8.67%	1,560	86,667

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.